MPW #	Geometry	Reservation Close Date*	CDRS Submit Date[@]	Cancellation Deadline	Dry Run DRC CutOff	Other Participants Tapeout Date[#&]	Customer Tapeout Date[#]	Projected 1st Batch Bare Die Ship[$]	Projected 2nd Batch Bare Die Ship[$]	Process Offering
MPW18G6	0.18um	10/11/2021	10/18/2021	11/8/2021	11/22/2021	11/22/2021	12/6/2021	Early Feb 2022-End Feb 2022	Mid Mar 2022-Mid Mar 2022	Fab35_IC/BCDlite/UHV/MCU
MPW2243	22nm	9/27/2021	10/4/2021	10/25/2021	11/8/2021	11/8/2021	11/22/2021	Mid Jan 2022-End Jan 2022	Early Feb 2022-Mid Feb 2022	22FDX/22FDX-ATV
MPW3A03	0.13um_200mm	9/21/2021	9/28/2021	10/20/2021	11/2/2021	11/2/2021	11/15/2021	Mid Feb 2022-Mid Feb 2022	Mid Mar 2022-Mid Mar 2022	F35_130UM_BCDSOI
MPW06A6	55nm	9/21/2021	9/28/2021	10/19/2021	11/2/2021	11/2/2021	11/15/2021	End Jan 2022-End Jan 2022	End Mar 2022-End Mar 2022	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW4R09	45RFSOI_45nm	9/15/2021		10/13/2021	10/27/2021	10/27/2021	11/10/2021	Early Feb 2022-Mid Feb 2022	Mid Mar 2022-Early Apr 2022	45RF
MPW0469	40nm	9/14/2021	9/21/2021	10/12/2021	10/26/2021	10/26/2021	11/8/2021	End Jan 2022-End Jan 2022	End Mar 2022-End Mar 2022	40LP/40LP-ESF3/40RF
MPW9H12	9HP_90nm	9/8/2021		10/6/2021	10/20/2021	10/20/2021	11/3/2021	Mid Mar 2022-End Mar 2022	Mid Mar 2022-End Mar 2022	9HP
MPW8X07	8XP_0.13um	8/25/2021		9/23/2021	10/6/2021	10/6/2021	10/20/2021	Early Mar 2021-Mid Mar 2021	Early Mar 2021-Mid Mar 2021	8XP
MPW8S04	8SW_0.13um	8/23/2021		9/21/2021	10/4/2021	10/4/2021	10/18/2021	Mid Feb 2022-Mid Feb 2022	Mid Feb 2022-Mid Feb 2022	8SW
MPW5P02	5PA4_0.35um	8/18/2021		9/15/2021	9/29/2021	9/29/2021	10/13/2021	Early Mar 2022-Mid Mar 2022	Mid Mar 2022-Early Apr 2022	5PA4

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MPW4C02	45SPCLO_45nm	8/18/2021	8/25/2021	9/15/2021	9/29/2021	9/29/2021	10/13/2021	Mid Feb 2022-End Feb 2022	Early Apr 2022-Mid Apr 2022	45SPCLO
MPW13B8	0.11/0.13um	8/16/2021	8/23/2021	9/14/2021	9/27/2021	9/27/2021	10/11/2021	Early Dec 2021-Mid Dec 2021	Early Feb 2022-Early Feb 2022	RFSOI/G/LP/EEPROM/110TS/BCDlite/BCD
MPW0365	28nm	8/16/2021	8/23/2021	9/14/2021	9/27/2021	9/27/2021	10/11/2021	Mid Dec 2021-End Dec 2021	Early Jan 2022-Mid Jan 2022	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW1512	0.15um	8/9/2021	8/16/2021	9/7/2021	9/20/2021	9/20/2021	10/4/2021	Mid Dec 2021-Mid Dec 2021	Early Jan 2022-Early Jan 2022	F35_MCU
MPW18G5	0.18um	7/26/2021	8/2/2021	8/24/2021	9/6/2021	9/6/2021	9/20/2021	End Nov 2021-Early Dec 2021	Early Jan 2022-Early Jan 2022	Fab35_IC/BCDlite/UHV/MCU
MPW06A5	65nm	7/26/2021	8/2/2021	8/24/2021	9/6/2021	9/6/2021	9/20/2021	End Nov 2021-End Nov 2021	Early Jan 2022-Early Jan 2022	65G/65LPE
MPW2242	22nm	7/26/2021	8/2/2021	8/23/2021	9/6/2021	9/6/2021	9/20/2021	Mid Nov 2021-End Nov 2021	Early Dec 2021-Mid Dec 2021	22FDX/22FDX-ATV/22eMRAM. Projected ship dates are for NON-22eMRAM.
MPW8N03	130NSX1_0.13um	7/21/2021		8/19/2021	9/1/2021	9/1/2021	9/15/2021	End Jan 2022-Early Feb 2022	End Jan 2022-Early Feb 2022	130NSX1
MPW06A4	55nm	7/19/2021	7/26/2021	8/17/2021	8/30/2021	8/30/2021	9/13/2021	End Nov 2021-End Nov 2021	End Jan 2022-End Jan 2022	55LPX/55LPe/55ULP/55BCDL/55HV
								End Oct 2021-End	End Dec	

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MPW13B7	0.11/0.13um	6/28/2021	7/5/2021	7/27/2021	8/9/2021	8/9/2021	8/23/2021	Oct 2021	2021-End Dec 2021	RFSOI/BCDlite/BCD

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MPW9H11	9HP_90nm	6/23/2021		7/21/2021	8/4/2021	8/4/2021	8/18/2021	Early Jan 2022-Mid Jan 2022	Early Jan 2022-Mid Jan 2022	9HP
MPW1101	0.11um_200mm	6/21/2021	6/28/2021	7/20/2021	8/2/2021	8/2/2021	8/16/2021	Mid Nov 2021-Mid Nov 2021	Early Dec 2021-Early Dec 2021	F35_110UM_MCU
MPW0468	40nm	6/21/2021	6/28/2021	7/20/2021	8/2/2021	8/2/2021	8/16/2021	Early Nov 2021-Early Nov 2021	Early Jan 2022-Early Jan 2022	40LP/40LP-ESF3/40RF
MPW8X06	8XP_0.13um	6/2/2021		7/1/2021	7/14/2021	7/14/2021	7/28/2021	Early Dec 2021-Mid Dec 2021	Early Dec 2021-Mid Dec 2021	8XP
MPW4E00	45RFE_45nm	6/2/2021	6/9/2021	6/30/2021	7/14/2021	7/14/2021	7/28/2021	Early Nov 2021-Mid Nov 2021	Mid Nov 2021-End Nov 2021	45RFE
MPW06A3	55nm	5/31/2021	6/7/2021	6/29/2021	7/12/2021	7/12/2021	7/26/2021	Early Oct 2021-Early Oct 2021	Early Dec 2021-Early Dec 2021	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW2241	22nm	5/24/2021	5/31/2021	6/21/2021	7/5/2021	7/5/2021	7/19/2021	Mid Sept 2021-End Sept 2021	Early Oct 2021-Mid Oct 2021	22FDX/22FDX-ATV
MPW4R08	45RFSOI_45nm	5/19/2021		6/16/2021	6/30/2021	6/30/2021	7/14/2021	Mid Oct 2021-End Oct 2021	Mid Nov 2021-Early Dec 2021	45RF
MPW4C01	45SPCLO_45nm	5/19/2021	5/26/2021	6/16/2021	6/30/2021	6/30/2021	7/14/2021	End Nov 2021-Early Dec 2021	Early Jan 2022-Mid Jan 2022	45SPCLO
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MPW0364	28nm	5/17/2021	5/24/2021	6/15/2021	6/28/2021	6/28/2021	7/12/2021	2021-End Sept 2021	2021-Early Oct 2021	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3

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MPW3A02	0.13um_200mm	5/10/2021	5/17/2021	6/8/2021	6/21/2021	6/21/2021	7/5/2021	Early Oct 2021-Early Oct 2021	End Oct 2021-End Oct 2021	F35_130UM_BCDSOI
MPW8S03	8SW_0.13um	5/3/2021		6/1/2021	6/14/2021	6/14/2021	6/28/2021	End Oct 2021-End Oct 2021	End Oct 2021-End Oct 2021	8SW
MPW18G4	0.18um	4/26/2021	5/3/2021	5/25/2021	6/7/2021	6/7/2021	6/21/2021	End Aug 2021-End Sept 2021	Early Oct 2021-Early Oct 2021	Fab35_IC/BCDlite/UHV/MCU
MPW13B6	0.11/0.13um	4/19/2021	4/26/2021	5/18/2021	5/31/2021	5/31/2021	6/14/2021	Mid Aug 2021-Mid Aug 2021	Mid Oct 2021-Mid Oct 2021	RFSOI/G/LP/EEPROM/110TS/BCDlite/BCD
MPW5P01	5PA4_0.35um	4/14/2021		5/12/2021	5/26/2021	5/26/2021	6/9/2021	Mid Oct 2021-End Oct 2021	End Oct 2021-Mid Nov 2021	5PA4
MPW1511	0.15um	4/12/2021	4/19/2021	5/11/2021	5/24/2021	5/24/2021	6/7/2021	Mid Aug 2021-Mid Aug 2021	Early Sept 2021-Early Sept 2021	F35_MCU
MPW06A2	55nm	4/5/2021	4/12/2021	5/4/2021	5/17/2021	5/17/2021	5/31/2021	Early Aug 2021-Mid Aug 2021	Early Oct 2021-Early Oct 2021	55LPX/55LPe/55ULP/55BCDL/55HV
MPW9H10	9HP_90nm	3/31/2021		4/28/2021	5/12/2021	5/12/2021	5/26/2021	Early Oct 2021-Mid Oct 2021	Early Oct 2021-Mid Oct 2021	9HP
MPW2240	22nm	3/29/2021	4/5/2021	4/26/2021	5/10/2021	5/10/2021	5/24/2021	Mid Jul 2021-End Jul 2021	Early Aug 2021-Mid Aug 2021	22FDX/22FDX-ATV/22eMRAM. Projected ship dates are for NON-22eMRAM.
MPW9W07	9WG_90nm	3/17/2021		4/14/2021	4/28/2021	4/28/2021	5/12/2021	Mid Sept 2021-Early Oct 2021	Mid Nov 2021-End Nov 2021	9WG

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MPW0467	40nm	3/8/2021	3/15/2021	4/6/2021	4/19/2021	4/19/2021	5/3/2021	End Jul 2021-End Jul 2021	Mid Sept 2021-Mid Sept 2021	40LP/40LP-ESF3/40RF
MPW06A1	65nm	3/1/2021	3/8/2021	3/30/2021	4/12/2021	4/12/2021	4/26/2021	End Jun 2021-Early Jul 2021	Mid Aug 2021-Mid Aug 2021	65G/65LPE
MPW8X05	8XP_0.13um	2/24/2021		3/24/2021	4/7/2021	4/7/2021	4/21/2021	Early Sept 2021-Mid Sept 2021	Early Sept 2021-Mid Sept 2021	8XP
MPW0363	28nm	2/22/2021	3/1/2021	3/23/2021	4/5/2021	4/5/2021	4/19/2021	End Jun 2021-Early Jul 2021	Early Jul 2021-Mid Jul 2021	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW8N02	130NSX1_0.13um	2/17/2021		3/18/2021	3/31/2021	3/31/2021	4/14/2021	End Aug 2021-Early Sept 2021	End Aug 2021-Early Sept 2021	130NSX1
MPW4C00	45SPCLO_45nm	2/17/2021	2/24/2021	3/17/2021	3/31/2021	3/31/2021	4/14/2021	End Aug 2021-Early Sept 2021	Early Oct 2021-Mid Oct 2021	45SPCLO
MPW13B5	0.11/0.13um	2/15/2021	2/22/2021	3/15/2021	3/29/2021	3/29/2021	4/12/2021	Mid Jun 2021-Mid Jun 2021	Mid Aug 2021-Mid Aug 2021	RFSOI/BCDlite/BCD
MPW06A0	55nm	2/1/2021	2/8/2021	3/2/2021	3/15/2021	3/15/2021	3/29/2021	Early Jun 2021-Mid Jun 2021	Early Aug 2021-Early Aug 2021	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW18G3	0.18um	2/1/2021	2/8/2021	3/2/2021	3/15/2021	3/15/2021	3/29/2021	End May 2021-Mid Jun 2021	Early Jul 2021-Early Jul 2021	Fab35_IC/BCDlite/UHV/MCU
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MPW2239	22nm	1/25/2021	2/1/2021	2/22/2021	3/8/2021	3/8/2021	3/22/2021	2021-End May 2021	2021-Mid Jun 2021	are for NON-22eMRAM.

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MPW1427	12nm	1/20/2021	1/27/2021	2/17/2021	3/3/2021	3/3/2021	3/17/2021	End Jun 2021-Early Jul 2021	Early Aug 2021-Mid Aug 2021	12LP
MPW3A01	0.13um_200mm	1/18/2021	1/25/2021	2/16/2021	3/1/2021	3/1/2021	3/15/2021	Mid Jun 2021-Mid Jun 2021	Mid Jul 2021-Mid Jul 2021	F35_130UM_BCDSOI
MPW4R07	45RFSOI_45nm	1/13/2021		2/11/2021	2/24/2021	2/24/2021	3/10/2021	Mid Jun 2021-End Jun 2021	Mid Jul 2021-Early Aug 2021	45RF
MPW8S02	8SW_0.13um	1/4/2021		2/2/2021	2/15/2021	2/15/2021	3/1/2021	Early Jul 2021-Early Jul 2021	Early Jul 2021-Early Jul 2021	8SW
MPW5P00	5PA4_0.35um	12/30/2020		1/27/2021	2/10/2021	2/10/2021	2/24/2021	Mid Jul 2021-End Jul 2021	End Jul 2021-Mid Aug 2021	5PA4
MPW0466	40nm	12/28/2020	1/4/2021	1/26/2021	2/8/2021	2/8/2021	2/22/2021	Mid May 2021-Mid May 2021	Early Jul 2021-Early Jul 2021	40LP/40LP-ESF3/40RF
MPW1510	0.15um	12/28/2020	1/4/2021	1/26/2021	2/8/2021	2/8/2021	2/22/2021	Early May 2021-Early May 2021	End May 2021-End May 2021	F35_MCU
MPW9H09	9HP_90nm	12/23/2020		1/20/2021	2/3/2021	2/3/2021	2/17/2021	Early Jul 2021-Mid Jul 2021	Early Jul 2021-Mid Jul 2021	9HP
MPW13B4	0.11/0.13um	12/7/2020	12/14/2020	1/5/2021	1/18/2021	1/18/2021	2/1/2021	Early Apr 2021-Early Apr 2021	Early Jun 2021-Early Jun 2021	RFSOI/G/LP/EEPROM/110TS/BCDlite/BCD
MPW8X04	8XP_0.13um	12/2/2020		12/31/2020	1/13/2021	1/13/2021	1/27/2021	Mid Jun 2021-End Jun 2021	Mid Jun 2017-End Jun 2021	8XP

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MPW0362	28nm	11/30/2020	12/7/2020	12/29/2020	1/11/2021	1/11/2021	1/25/2021	End Apr 2021-Early May 2021	Mid May 2021-End May 2021	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW2238	22nm	11/30/2020	12/7/2020	12/28/2020	1/11/2021	1/11/2021	1/25/2021	End Mar 2021-Early Apr 2021	Early Apr 2021-Mid Apr 2021	22FDX/22FDX-ATV/22eMRAM. Projected ship dates are for NON-22eMRAM.
MPW9W06	9WG_90nm	11/25/2020		12/23/2020	1/6/2021	1/6/2021	1/20/2021	Early Jun 2021-Mid Jun 2021	Early Aug 2021-Mid Aug 2021	9WG
MPW1426	12nm	10/31/2020	10/28/2020	11/18/2020	12/2/2020	12/2/2020	12/16/2020	Mid Mar 2021-End Mar 2021	Early May 2021-Mid May 2021	12LP
MPW8S01	8SW_0.13um	10/25/2020		11/23/2020	12/6/2020	12/6/2020	12/20/2020	End Apr 2021-End Apr 2021	End Apr 2021-End Apr 2021	8SW
MPW4R06	45RFSOI_45nm	10/24/2020		10/6/2020	10/19/2020	10/19/2020	11/7/2020	Early Feb 2021-Early Mar 2021	Early Mar 2021-End Mar 2021	45RF
MPW8X03	8XP_0.13um	10/19/2020		11/16/2020	11/30/2020	11/30/2020	12/14/2020	End Apr 2021-Early May 2021	End Apr 2021-Mid May 2021	8XP
MPW0699	55nm	10/12/2020	10/19/2020	11/10/2020	11/23/2020	11/23/2020	12/7/2020	Mid Feb 2021-Early Mar 2021	End Apr 2021-Early May 2021	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW18G2	0.18um	10/12/2020	10/19/2020	11/9/2020	11/23/2020	11/23/2020	12/7/2020	Early Feb 2021-End Feb 2021	Mid Mar 2021-Mid Mar 2021	Fab35_IC/BCDlite/UHV/MCU
MPW8H05	8HP_0.13um	10/5/2020		11/2/2020	11/16/2020	11/16/2020	11/30/2020	End Mar 2021-Early Apr	End Mar 2021-Early Apr	8HP_0.13um

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MPW8N01	130NSX1_0.13um	9/21/2020		10/20/2020	11/2/2020	11/2/2020	11/16/2020	Early Apr 2021-Mid Apr 2021	Early Apr 2021-Mid Apr 2021	130NSX1
MPW2237	22nm	9/15/2020	9/22/2020	10/13/2020	10/27/2020	10/27/2020	11/9/2020	Early Jan 2021-Mid Jan 2021	End Jan 2021-Early Feb 2021	22FDX/22eMRAM. Projected ship dates are for NON-22eMRAM.
MPW069A	55nm	9/14/2020	9/21/2020	10/13/2020	10/26/2020	10/26/2020	11/9/2020	Mid Oct 2020-End Oct 2020	Mid Dec 2020-End Dec 2020	55LPX/55LPe/55ULP/55BCDL/55DDI
MPW9W05	9WG_90nm	9/11/2020		10/10/2020	10/23/2020	10/23/2020	11/6/2020	Mid Mar 2021-End Mar 2021	Mid May 2021-End May 2021	9WG
MPW13B3	0.11/0.13um	9/7/2020	9/14/2020	10/6/2020	10/19/2020	10/19/2020	11/2/2020	Early Jan 2021-Early Jan 2021	Early Mar 2021-Early Mar 2021	RFSOI/G/LP/EEPROM/110TS/BCDlite/BCD
MPW0465	40nm	9/7/2020	9/14/2020	10/5/2020	10/19/2020	10/19/2020	11/2/2020	End Jan 2021-End Jan 2021	End Mar 2021-End Mar 2021	40LP/40NVM/40RF
MPW1509	0.15um	8/31/2020	9/7/2020	9/29/2020	10/12/2020	10/12/2020	10/26/2020	End Dec 2020-End Dec 2020	End Jan 2021-End Jan 2021	F35_MCU
MPW9H08	9HP_90nm	8/31/2020		9/29/2020	10/12/2020	10/12/2020	10/26/2020	Early Mar 2021-Mid Mar 2021	Early Mar 2021-Mid Mar 2021	9HP
MPW0698	55nm	8/24/2020	8/31/2020	9/22/2020	10/5/2020	10/5/2020	10/19/2020	End Dec 2020-Early Jan 2021	Early Mar 2021-Early Mar 2021	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW0361	28nm	8/11/2020	8/17/2020	9/8/2020	9/21/2020	9/21/2020	10/5/2020	Mid Dec 2020-End Dec 2020	End Dec 2020-Mid Jan 2021	28SLP/28SLPe/28SLP-RF/28SLP-HV

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MPW18G1	0.18um	8/3/2020	8/10/2020	9/1/2020	9/14/2020	9/14/2020	9/28/2020	End Nov 2020-Mid Dec 2020	Early Jan 2021-Early Jan 2021	Fab35_IC/BCDlite/UHV/MCU
MPW1425	12nm	7/29/2020	8/5/2020	8/27/2020	9/9/2020	9/9/2020	9/23/2020	Mid Dec 2020-End Dec 2020	End Jan 2021-Early Feb 2021	12LP
MPW13B2	0.11/0.13um	7/27/2020	8/3/2020	8/25/2020	9/7/2020	9/7/2020	9/21/2020	End Nov 2020-End Nov 2020	End Jan 2021-End Jan 2021	RFSOI/LP/EEPROM/110TS/BCDlite/BCD
MPW2236	22nm	7/20/2020	7/27/2020	8/18/2020	8/31/2020	8/31/2020	9/14/2020	Early Nov 2020-Mid Nov 2020	End Nov 2020-Early Dec 2020	22FDX/22eMRAM. Projected ship dates are for NON-22eMRAM.
MPW0696	55nm	6/29/2020	7/6/2020	7/28/2020	8/10/2020	8/10/2020	8/24/2020	Early Nov 2020-Early Nov 2020	Early Jan 2021-Early Jan 2021	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW4R05	45RFSOI_45nm	6/23/2020		7/22/2020	8/4/2020	8/4/2020	8/18/2020	Early Dec 2020-Mid Dec 2020	Mid Jan 2021-End Jan 2021	45RF
MPW0464	40nm	6/22/2020	6/29/2020	7/20/2020	8/3/2020	8/3/2020	8/17/2020	Early Nov 2020-Early Nov 2020	Early Jan 2021-Early Jan 2021	40LP
MPW9H07	9HP_90nm	6/15/2020		7/13/2020	7/27/2020	7/27/2020	8/10/2020	End Dec 2020-Early Jan 2021	End Dec 2020-Early Jan 2021	9HP
MPW9H0A	9HP_90nm	6/8/2020		6/9/2020	6/8/2020	6/8/2020	6/18/2020	Mid Oct 2020-End Oct 2020	End Oct 2020-Mid Nov 2020	9HP
MPW9W04	9WG_90nm	6/8/2020		7/7/2020	7/20/2020	7/20/2020	8/3/2020	Mid Dec 2020-End Dec 2020	Early Feb 2021-Mid Feb 2021	9WG

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MPW8X02	8XP_0.13um	6/1/2020		6/30/2020	7/13/2020	7/13/2020	7/27/2020	Early Dec 2020-Mid Dec 2020	Early Dec 2020-Mid Dec 2020	8XP
MPW1424	12nm	4/28/2020	5/5/2020	5/27/2020	6/9/2020	6/9/2020	7/7/2020	Mid Oct 2020-End Oct 2020	End Nov 2020-Early Dec 2020	12LP
MPW7W01	7WL_0.18um	4/27/2020		5/26/2020	6/8/2020	6/8/2020	6/22/2020	Early Nov 2020-Mid Nov 2020	Early Nov 2020-Mid Nov 2020	7WL_0.18um
MPW8H04	8HP_0.13um	4/27/2020		5/26/2020	6/8/2020	6/8/2020	6/22/2020	Early Nov 2020-Mid Nov 2020	Early Nov 2020-Mid Nov 2020	8HP_0.13um

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